



HPEC: Looking Back and Projecting Forward

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2006 High Performance Embedded Computing Workshop

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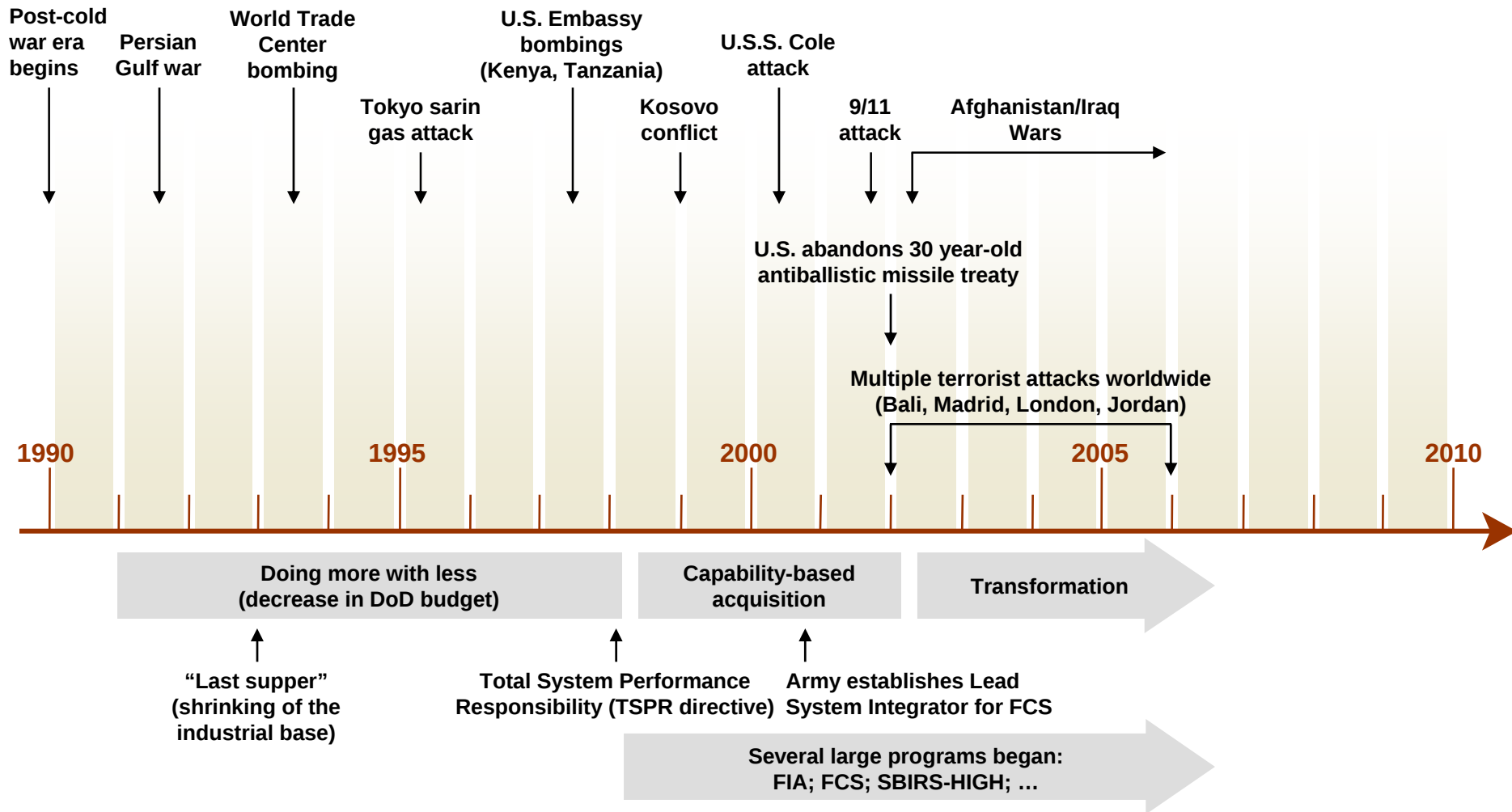


Outline

- ➔ • **Big Picture Over Past Decade**
 - **HPEC Representative Developments**
 - **DoD Landscape and Impact on HPEC**
 - **The Next Decade and Net-Centric Architectures**
 - **Summary**

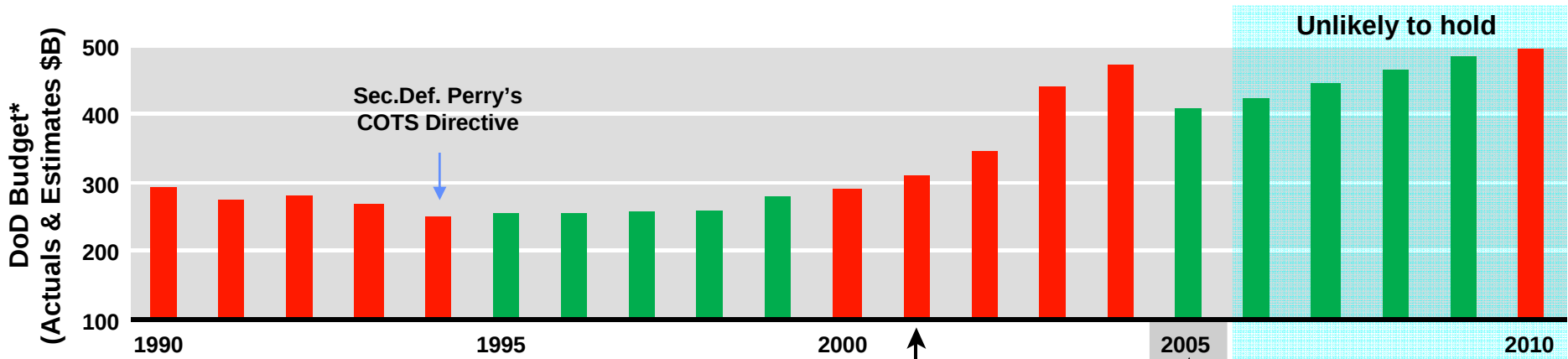


World Events and Directives Impacting DoD Investments





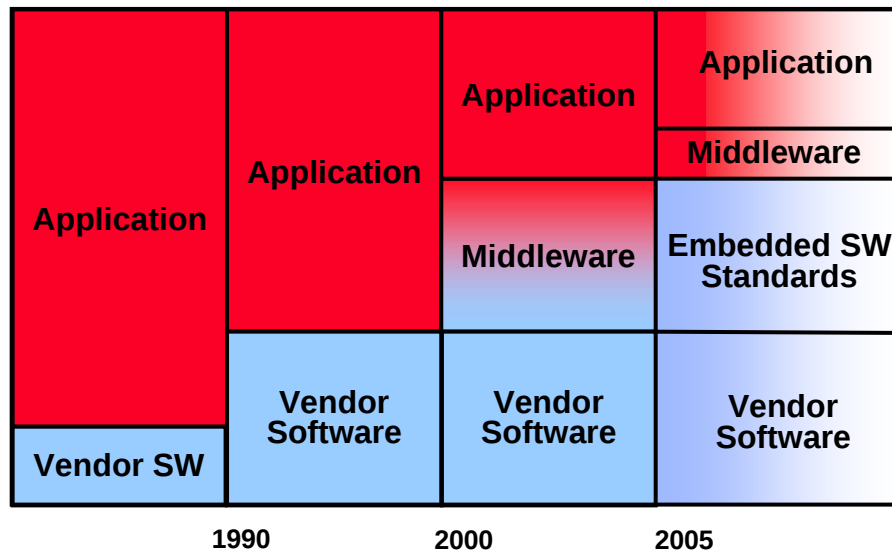
DoD Budget and QDR Focus



* Source: U.S. Office of Management and Budget

DoD Software

COTS development

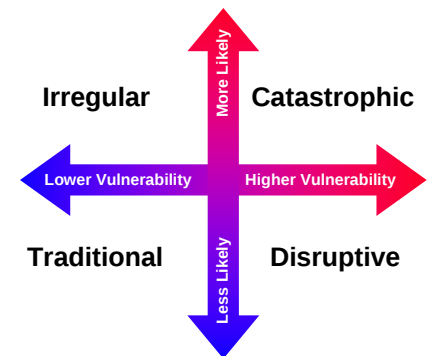


2001 Quadrennial Defense Review (from threat-based to capability-based acquisition)

2005 Quadrennial Defense Review

Reductions in next five years likely

Security Challenges





High Performance Embedded Computing

- A Historical Perspective -

1997-1998

1999-2000

2001-2002

2003-2004

2005-2006

2007+

Computing Systems



Intel Paragon & STAP Processor

- 40-50 MHz clock
- <0.1 to 12 MFLOPS per watt



AFRL HPCS & Improved Space Processor Architecture

- 200-333 MHz clock
- 30-40 MOPS per watt



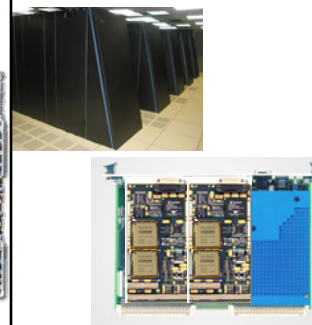
NEC Earth Simulator & Mk 48 CBASS BSAR

- 80-500 MHz clock
- 60-90 MFLOPS per watt



LLGrid System & KASSPER

- 500 MHz - 2.8 GHz clock
- 65-320 MFLOPS per watt



IBM Blue Gene & WorldScope Scalable Processing Platform

- 250-700 MHz clock
- 200 MFLOPS – 100s GFLOPS per watt



Net-centric / service-oriented architectures & unmanned platforms

- 1000s GFLOPS per watt

Enabling Technologies

- VSIPL & MPI standards
- Adaptive Computing Systems / Reconfigurable Computing

- Data Reorg forum
- High-performance CORBA
- VLSI Photonics
- Polymorphous Computing Architectures

- High-performance embedded interconnects
- Parallel MATLAB
- Cognitive Processing
- Integrated ASICs, FGPAs, and prog. devices

- Grid computing
- VXS (VME Switched Serial) draft standard

- VSIPL++ standard
- Multi-core processors

- Self-organizing wireless sensor networks
- Global Information Grid
- Distributed computing and storage



HPEC Workshop Highlights

1997

- keynote: RADM K. Paige, USN
- 1st HPEC
- VSIPL API v1.0 released

1998

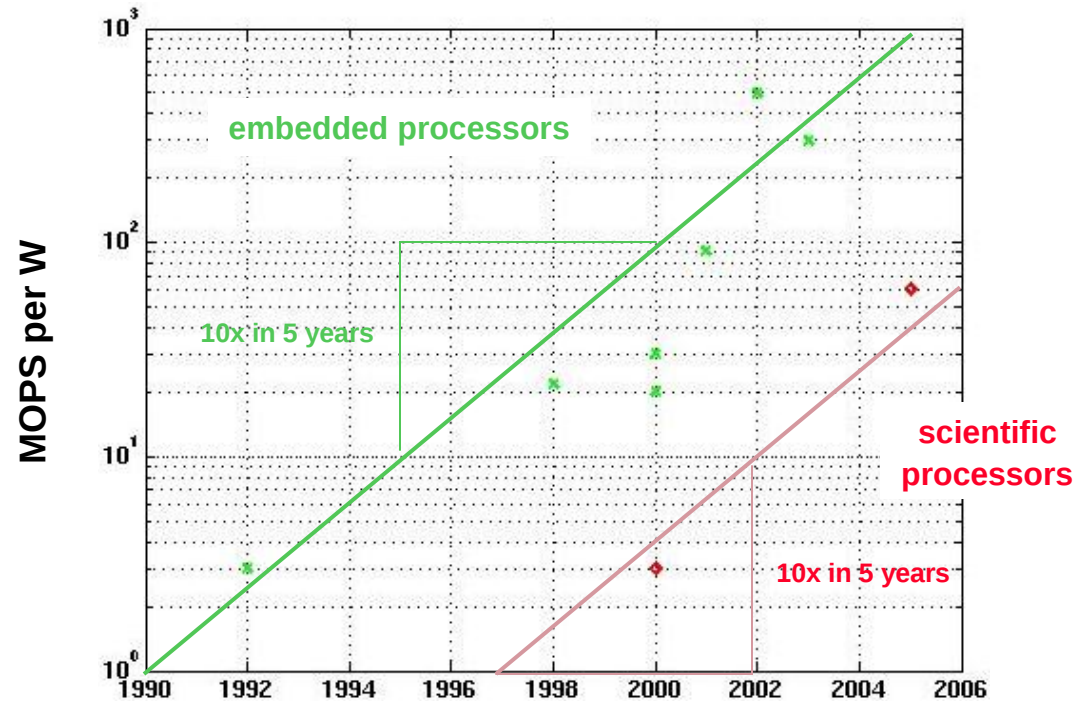
- keynote: F. Perry, SPAWAR
- 1st session dedicated to reconfigurable computing
- MPI/RT API v1.0 released

1999

- keynote: D. Tennenhouse, DARPA
- banquet: T. Sterling, JPL
- 1st banquet speaker

2000

- keynote: C. Holland, DUSD
- banquet: C. Williams, JPL
- 1st BAA/program announcement



2001

- keynote: G. Bell, Microsoft
- banquet: T. Knight, MIT AI Lab
- 1st session dedicated to parallel MATLAB

2002

- keynote: Maj Gen P Nielsen, USAF
- banquet: Cleve Moler, The Mathworks
- 1st VSIPL++ talk

2003

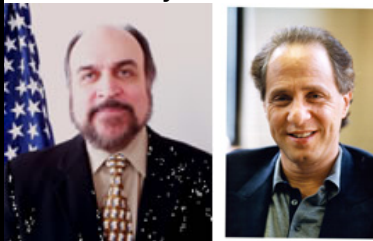
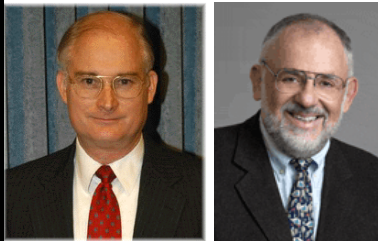
- keynote: J. Parmentola, ADRLM
- banquet: R. Kurzweil, Kurzweil Technologies
- 1st US-only session

2004

- keynote: D. Patterson, UC Berkeley
- banquet: M. Flynn, Stanford
- Grid computing

2005

- keynote: Brig Gen G. Connor, USAF
- banquet: M. Cusumano, MIT
- Cell processor





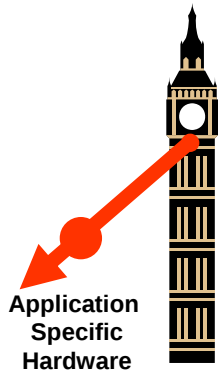
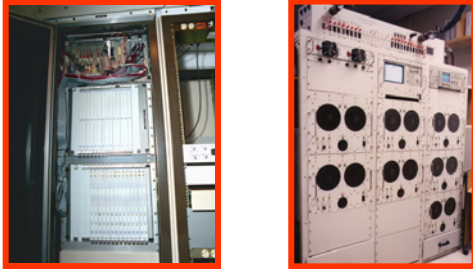
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- **Big Picture Over Past Decade**
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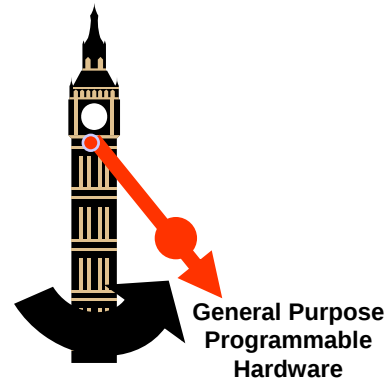
A Decade of Embedded Computing

Late 1980s - Early 1990s



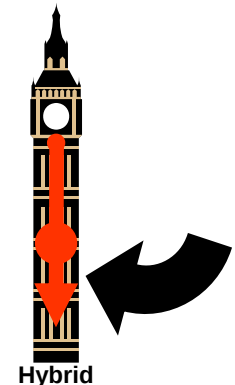
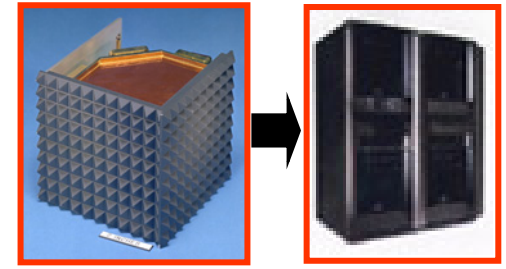
- Custom design
- COTS parts
- Non-portable SW
- Application specific prototype demonstration

Mid-Late 1990s



- COTS HW
- Vendor specific SW
- Portable SW library
- Legacy SW
- June 1994- Sec. Def. Perry reduces reliance on military specs and standards: go commercial

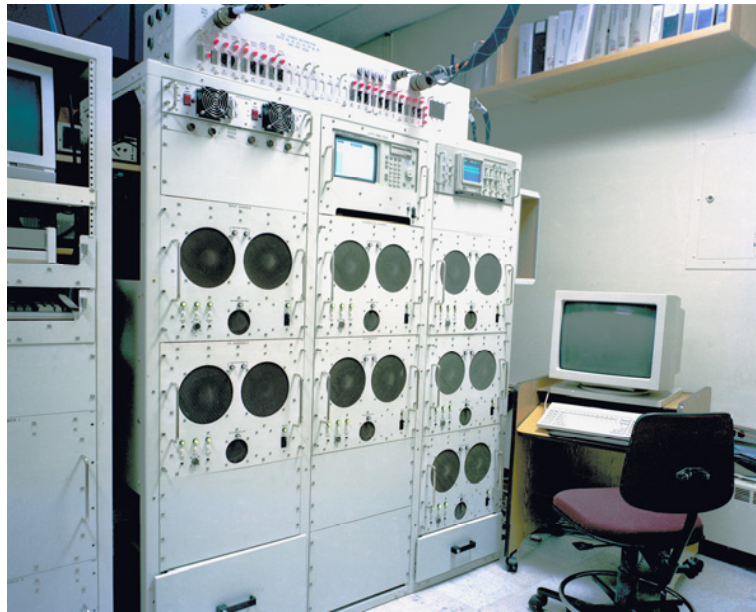
Early 2000s - Mid 2000s



- Balanced architectures
- Custom front-end HW followed by COTS back-end
- SW standards
- Leverages information technology from commercial sector



Early 90's Space-Time Adaptive Processor



HARDWARE OVERALL COMPLEXITY

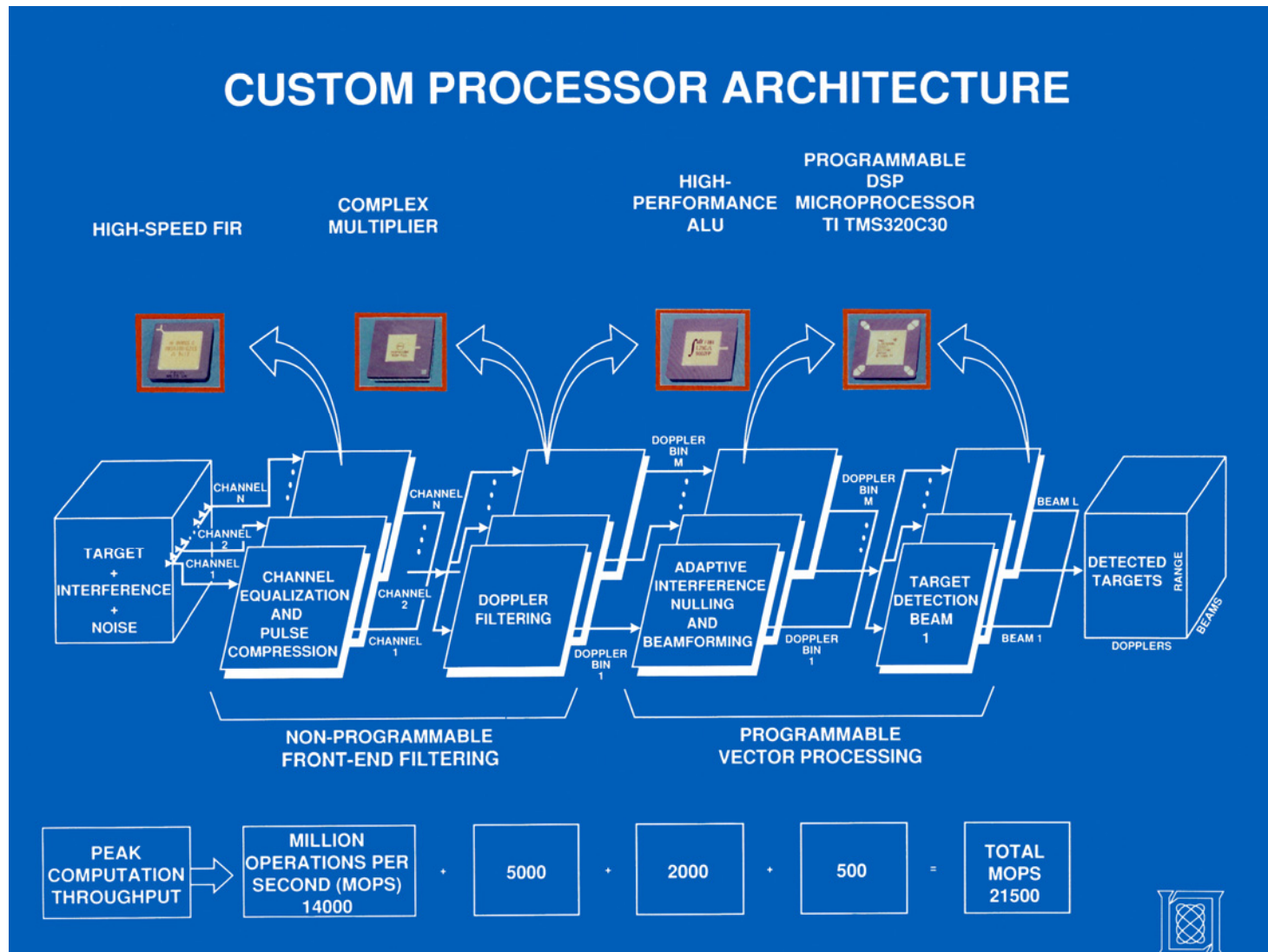
COMPONENT TYPE	TOTAL SIZE
IC (LSI and VLSI)	≈ 25,000
UNIQUE CUSTOM BOARD DESIGNS	13 BOARD DESIGNS I/O 288 PINS ≈ 200 ICs 125 SQUARE INCHES
TOTAL BOARDS	134 BOARDS 113 PRINTED CIRCUIT 21 WIRE WRAP
TOTAL CHASSIS	14 11 REAL-TIME SIGNAL PROCESSING 3 CONTROL 21 SLOT 9U VME



214899_3.ai



STAP Processor Top Level Architecture





Custom Design with COTS Components

CUSTOM DESIGN WITH OFF-THE-SHELF COMPONENTS

HIGH-THROUGHPUT FIR FILTER



- INMOS A100**
- 400 MOPS
 - 16-BIT DATA INPUT
 - 36-BIT ARITHMETIC
 - 16 COMPLEX TAPS
 - 6.25 MHz CLOCK (8-Bit Coefficients)
 - POWER < 2 W

COMPLEX MULTIPLIER



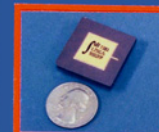
- PLESSEY PDSP16112**
- 16-BIT DATA INPUT
 - 12-BIT COEFFICIENTS
 - 10 MHz CLOCK
 - POWER < 500 mW

PROGRAMMABLE DSP MICROPROCESSOR



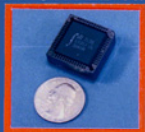
- TI TMS320C30**
- 33 MFLOPS
 - 32-BIT FLOATING-POINT
 - 60 ns INSTRUCTION
 - 2 K × 32 ON-CHIP RAM
 - 2 SERIAL PORTS
 - 33 MHz CLOCK
 - POWER < 2 W

HIGH-PERFORMANCE ALU



- IDT 7381**
- 16-BIT DATA INPUT
 - 16-BIT ARITHMETIC
 - 10 MHz CLOCK
 - POWER < 300 mW

DUAL-PORTED RAM



**INTEGRATED DEVICE TECHNOLOGY
IDT 7130**

- 1 K × 8
- ACCESS TIME 35 ns
- POWER < 800 mW

CMOS STATIC RAM



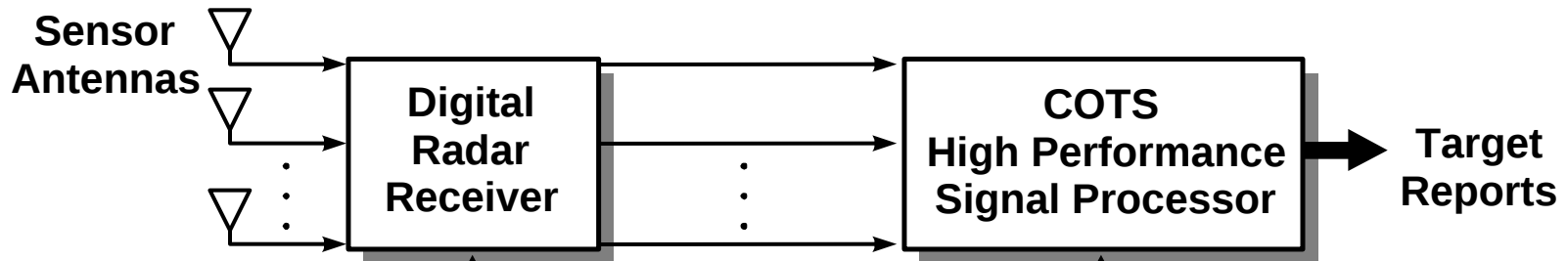
- SHARP LH521002**
- 256 K × 4
 - ACCESS TIME 25 ns
 - POWER < 400 mW



162040-2



Embedded Real-Time Signal Processor



- Reduction in hardware size
- Flexible waveform design
- High performance digital filtering functions
- 100–1000 billion operations per second



- Massively parallel processor
- Portable signal processing libraries
- Real-time performance
- 50–500 billion floating-point operations per second



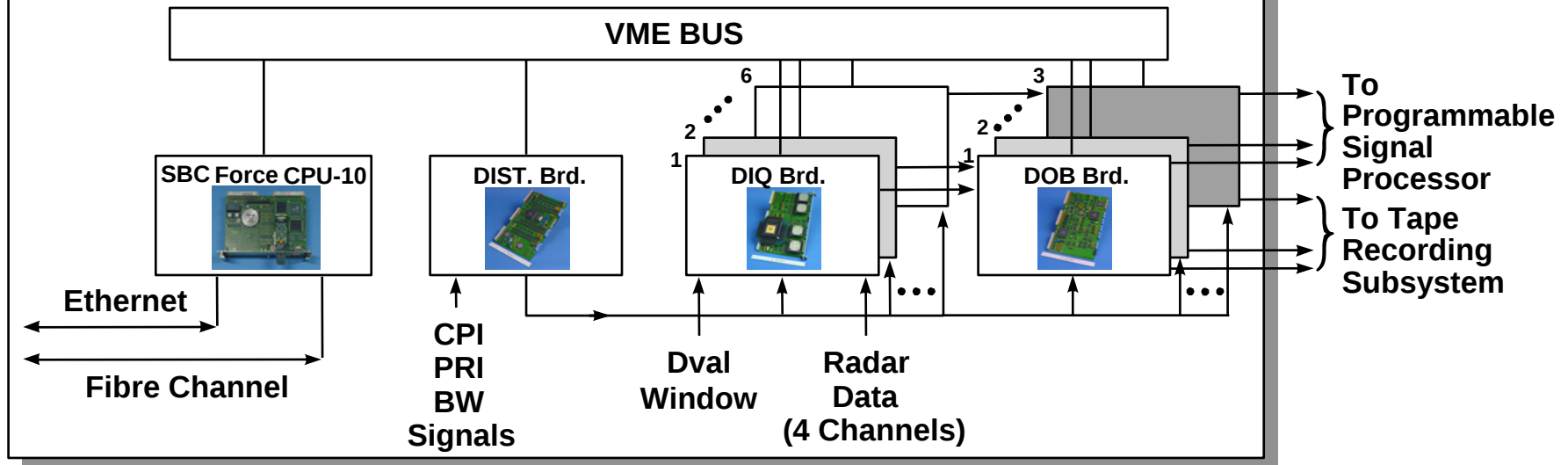
Front-End Processor Hardware



Hardware Features

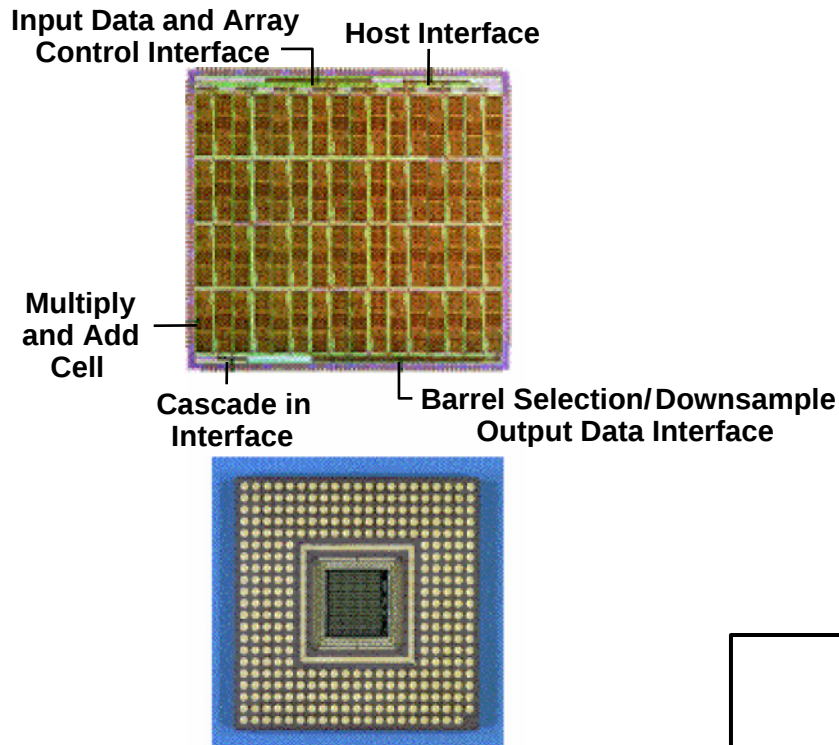
- Dedicated VLSI
- 100 GOPS
- Two 9U VME chassis
- Form factor:
 - 7.3 ft³
 - 210 lbs
 - 1.5 kW
- Throughput density:
 - 14 GOPS/ft³

Chassis Level Architecture





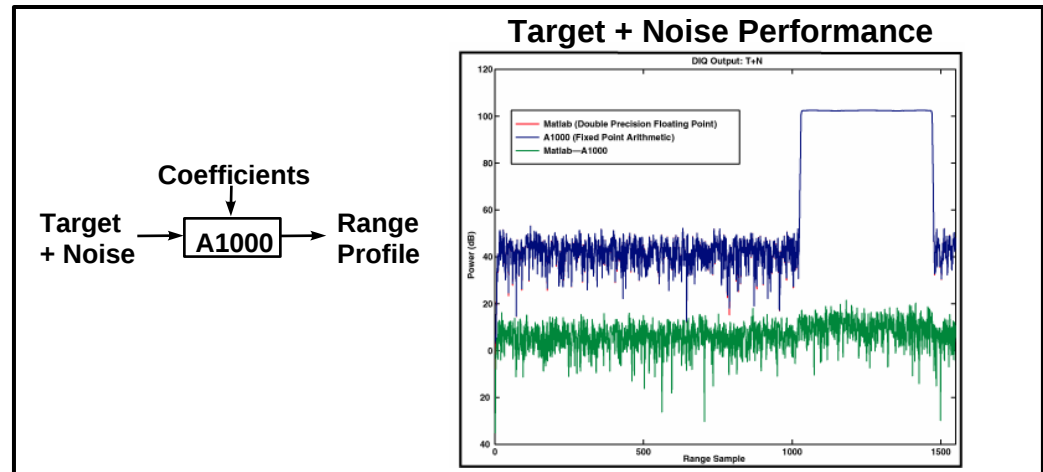
VLSI Custom Front-End Chip



ASIC Features

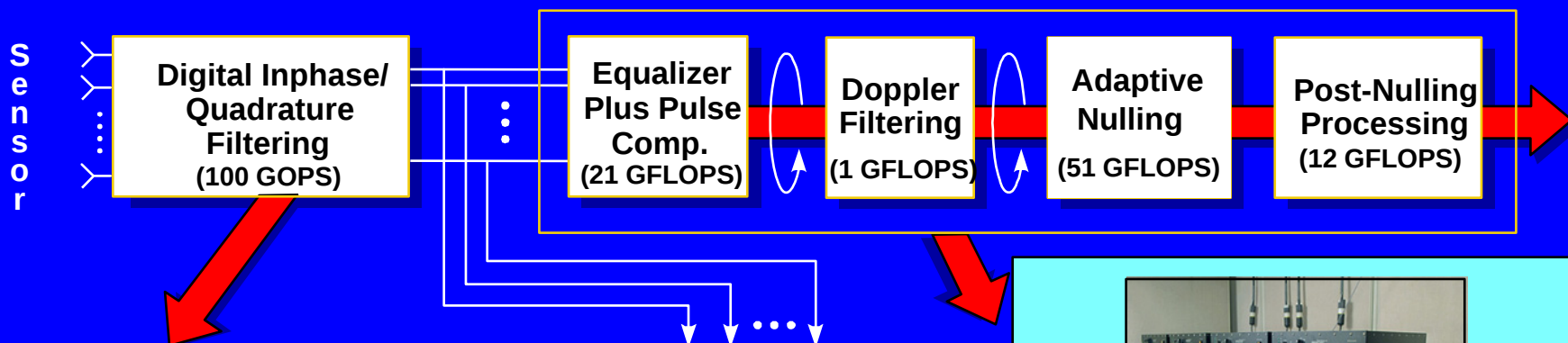
- 2 GOPS
- 585 mil x 585 mil die
- 1.5 Million transistors
- 0.65 μ CMOS
- Three-layer metal
- 4 Watts/chip

Performance Results





Airborne Signal Processor



Custom Hardware

- Dedicated VLSI
- 100 GOPS
- Two chassis
- Form factor
 - 7.3ft³
 - 210 lbs
 - 1.5 kW
- Throughput density = 14 GOPS/ft³



AMPEX Tape Recorder

- Tape recorder rate = 30 Mbytes/sec
- 1 Bit error every 240 CPI
- 25 min cassette capacity
- Recorded data = 30% of available data with 17% waveform



COTS Programmable Signal Processor

- SHARC AD21060 based
- 85 GFlops
- Bisection BW = 3.2 Gbytes/sec
- I/O throughput = 240 Mbytes/sec
- Four chassis
- Form factor
 - 33ft³
 - 812 lbs
 - 6.9 kW
- Throughput density = 2.2 GFLOPS/ft³



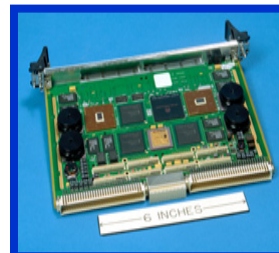
Hardware Advances in Signal Processor Systems

200 GOPS
40 ft³
1000 lbs
8.4 KW
22 MOPS/W



STAP Processor
1998

16 GFLOPS
< 1 ft³
2 lbs
31 W
500 MFLOPS/W



Missile Seeker
2002



432 GFLOPS
46 ft³
1200 lbs
7.2 KW
60 MFLOPS/W

Cluster
2005

1988 89 90 91 92 93 94 95 96 97 98 99 2000 01 02 03 04 05

Adaptive Processor
1992



22 GOPS
50 ft³
1400 lbs
8 KW
3 MOPS/W

AEGIS Surveillance Radar
2000



43 GFLOPS
110 ft³
1960 lbs
14 KW
3 MFLOPS/W



40 GFLOPS
7.5 ft³
200 lbs
2 KW
20 MFLOPS/W

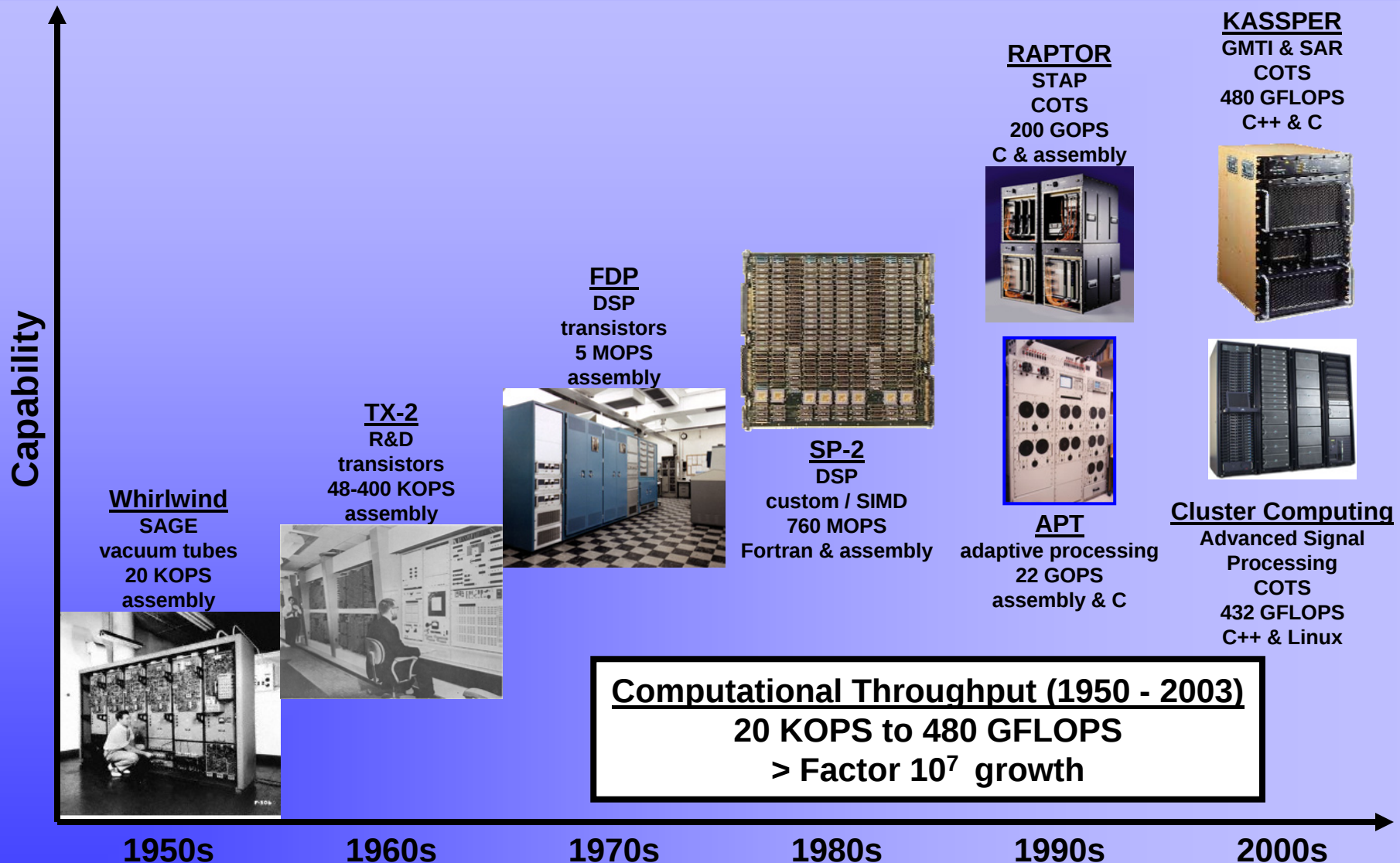
Knowledge Aided Radar
2003



450 GFLOPS
9 ft³
325 lbs
1.5 KW
300 MFLOPS/W



Historical Perspective on Systems and Software



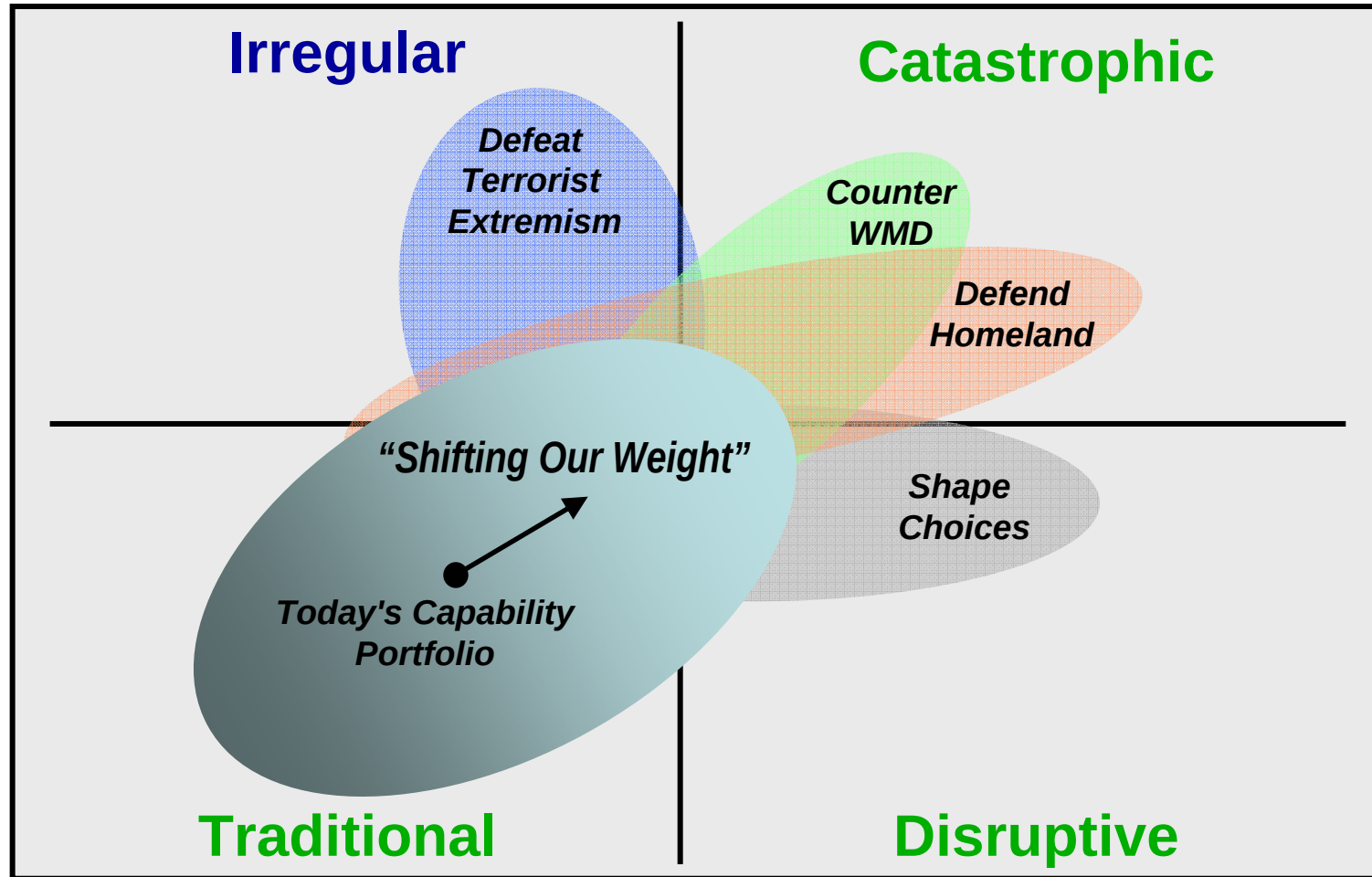


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DoD Quadrennial Defense Review



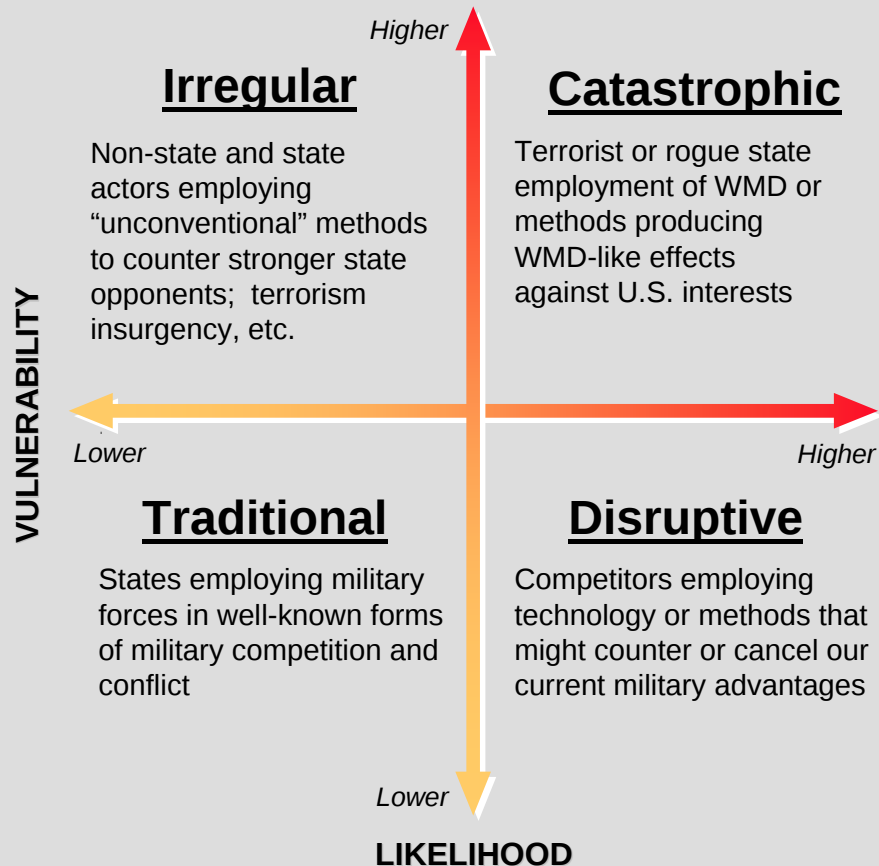
Continuing the reorientation of military capabilities and implementing enterprise-wide reforms to ensure structures and process support the President and the warfighter



DoD Options and Capabilities Provided

Provide more options for President, capabilities for CoComs

Post-9/11 Security Challenges



Capability Focus Areas

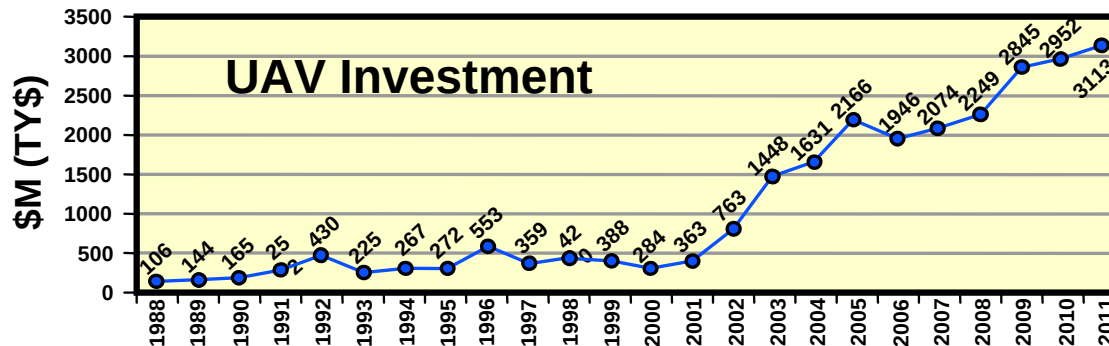
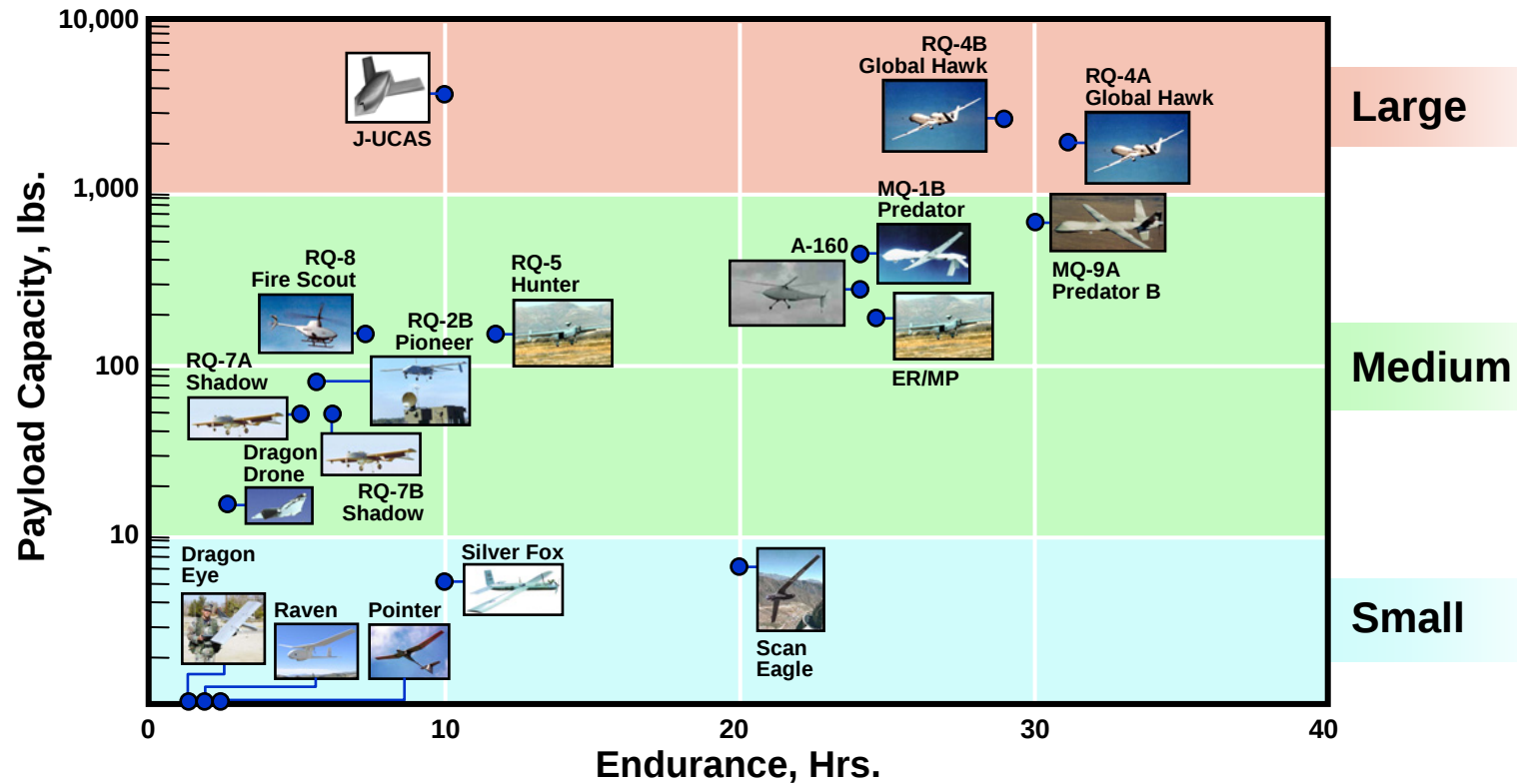
- Defeat terrorist networks
- Defend homeland in depth
- Prevent acquisition or use of WMD
- Shape choices of countries at strategic crossroads (Assure, Dissuade, Deter, Defeat)

Options
for
President

Capabilities
for
COCOMs



Growth in UAV Investment



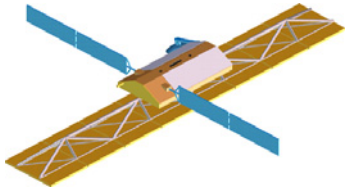


Next Generation Systems Employing Phased-Array Architectures

Challenges Facing Next Generation Systems

- Multi-Function System Capability
 - Programming Flexibility
 - Rapid context switching
- Increase Number of Phase Centers
 - High Computation Throughput
 - High Comm. and Memory
- Very constrained in form factor
 - Small size, weight and power
- Open system architecture

Space-Based Radar



JSTARS MPRTIP



Future Space-Based Radar



Navy Multi-Function Maritime Aircraft



Global Hawk MPRTIP



F-22



JSF DemVal



F/A-18 E/F



Navy Global Hawk



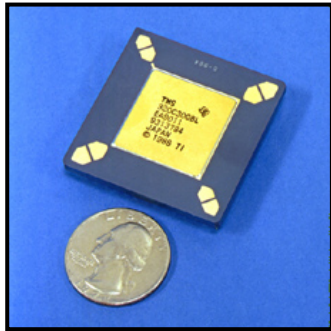
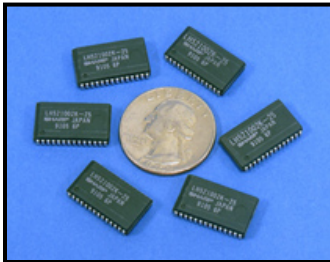


Functions-Platforms-Sensors Desired

Functions	Platforms	Sensors
Intelligence Surveillance - Space - Air - Ground - Ocean - Underwater - Subsurface	Land	Coherent Signal
Reconnaissance	Fixed sites, Vehicles Personnel, UGS, UGVs	Radar - SAR - MTI
Targeting	AIR	SIGINT
Monitoring	UAVs (large, small, micro)	Communication - RF - Laser
Fire Control	Aircraft, Aerostats, Blimps, Missiles, Shells	Seismic
Guidance	Sea	Acoustic
Communication	Ships, Submarines	Non-Coherent Signal
Mapping	Underwater Sites, UUV, Torpedoes	Electro-optic
Discrimination	Space	Infrared
ATR	Rockets	Multispectral
Imaging	Missiles	Hyperspectral
BDA	Satellites	Ultraspectral
Command, Control		Nuclear/
Coordination		Chemical/
Tasking		Biological
⋮		



Trends in Computing Technology



Microprocessors

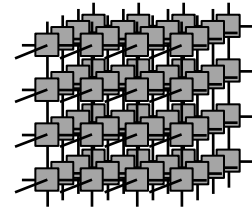
- ITRS* 2009 projections
 - Speed $\uparrow$ 60% / year
 - 773 M transistors
 - 52 nm half-pitch
 - 12 GHz clock speed
 - \$85 / chip (1st year)

*Reference: The International Technology Roadmap for Semiconductors (2005)

Memory

- Speed $\uparrow$ 7% / year
- ITRS* 2009 projections
 - 17 Gbits (2^{34} bits)/chip
 - 50 nm half-pitch
 - 0.8 - 1.0 V
 - \$223 / chip (1st year)

*Reference: The International Technology Roadmap for Semiconductors (2005)



System Interconnects

- Balanced architecture demands = 100s Gbytes for teraflops of computing
- Electrical based interconnects
 - Large power $\times$ volume product
 - Low performance for small message size transferred
 - Advances driven by commercial applications of network switching
- High-speed interconnects:
 - 10 Gbit Ethernet
 - 3GIO
 - HyperTransport / Infinipath
 - InfiniBand
 - Myrinet
 - QsNet
 - Rapid IO
 - SCI
 - StarFabric

Reference: Hot Interconnects Symposium
Website: www.hoti.org

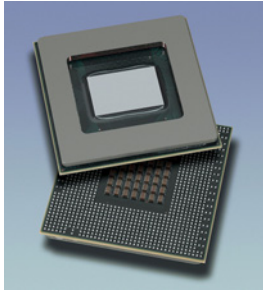
System-of-Systems Warfare in the Littoral Environment





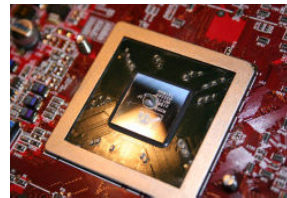
Critical HPEC Enablers

Cell Processor



- 3.2 GHz clock
- 200+ GFLOPS peak
- estimated 30-60 W

Graphics / Video Processors



- ATI
- NVidia
- 550 MHz; 300 million transistors
- 256-512 bit memory bus
- 1-2 TOPS



FPGAs



- Xilinx
 - 330K logic elements
 - 550 MHz clock
- Altera
 - 622 user I/O pins

Chassis



- ATR
- VME / VME64 / VME64x
- air, conduction, or liquid cooling
- shock isolated vs. hard mounted

Interconnects

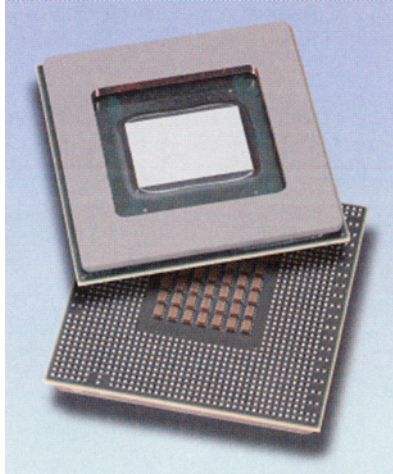
- 10 Gbit Ethernet
- 3GIO
- HyperTransport / Infinipath
- InfiniBand
- Myrinet
- QsNet
- RapidIO
- SCI
- StarFabric

Software

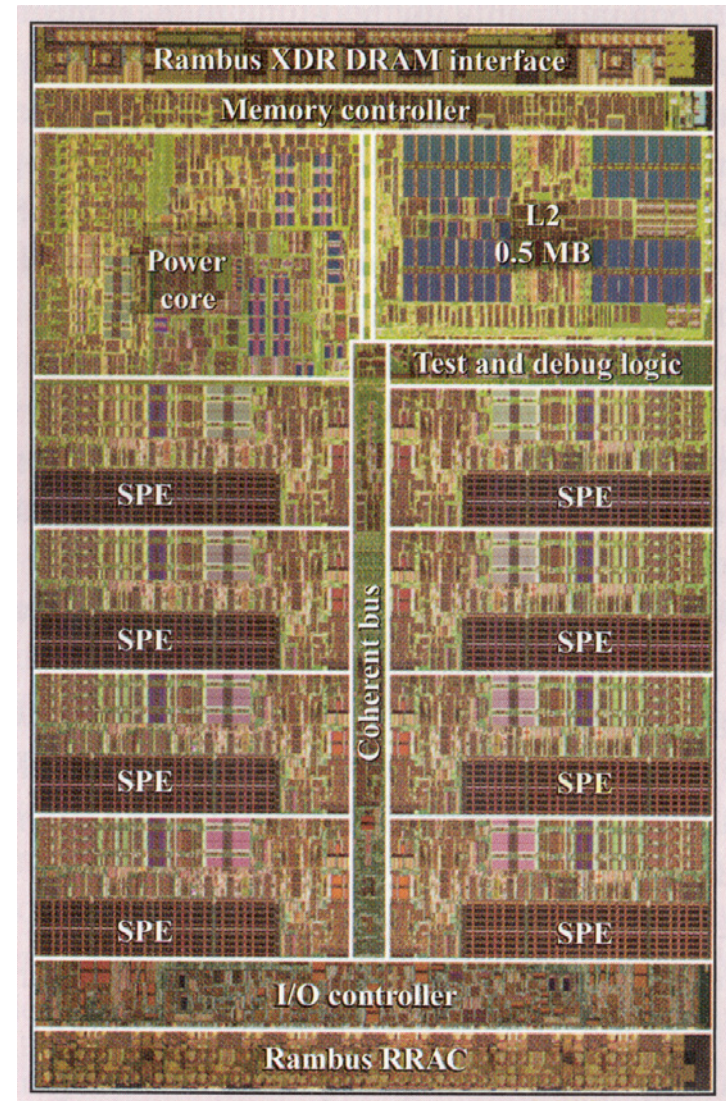
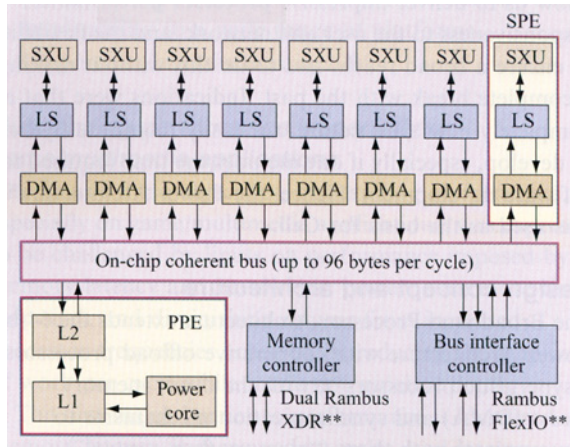
- VSIPL / VSIPL++
- MPI
- CORBA
- VxWorks
- Linux / RT Linux
- Service-Oriented Architecture
 - XML
 - WSDL
 - SOAP
 - UDDI



Cell Multi-Processor System



- Total peak performance over 200 GFLOPS running at 3.2 GHz
- 90 nm CMOS process
- 25.6 GBytes/sec to Rambus DRAM
- Up to 20 GBytes/sec communication bandwidth to graphics processor



Reference: IBM Journal of Research and Development, Sept. 2005.

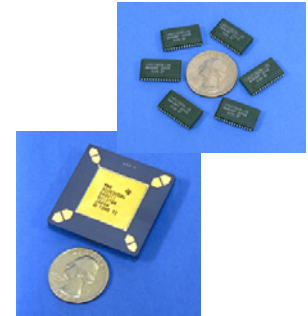
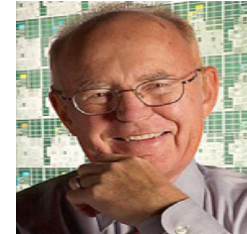
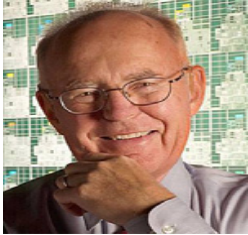


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Accuracy is more Important Than Precision when Projecting Forward



**“Cramming More Components
Onto Integrated Circuits,”
Dr. Gordon Moore
Electronics Magazine,
April 19, 1965
“2x/12 months”**

**Prof. Carver Mead Coins
the Term “Moore’s Law”**

**In 1975 Dr. Gordon Moore
amends
Original Statement to
“2x/24 months”**

**As Progress Continued
Industry Modified
Original Statement to
“2x/18 months”**

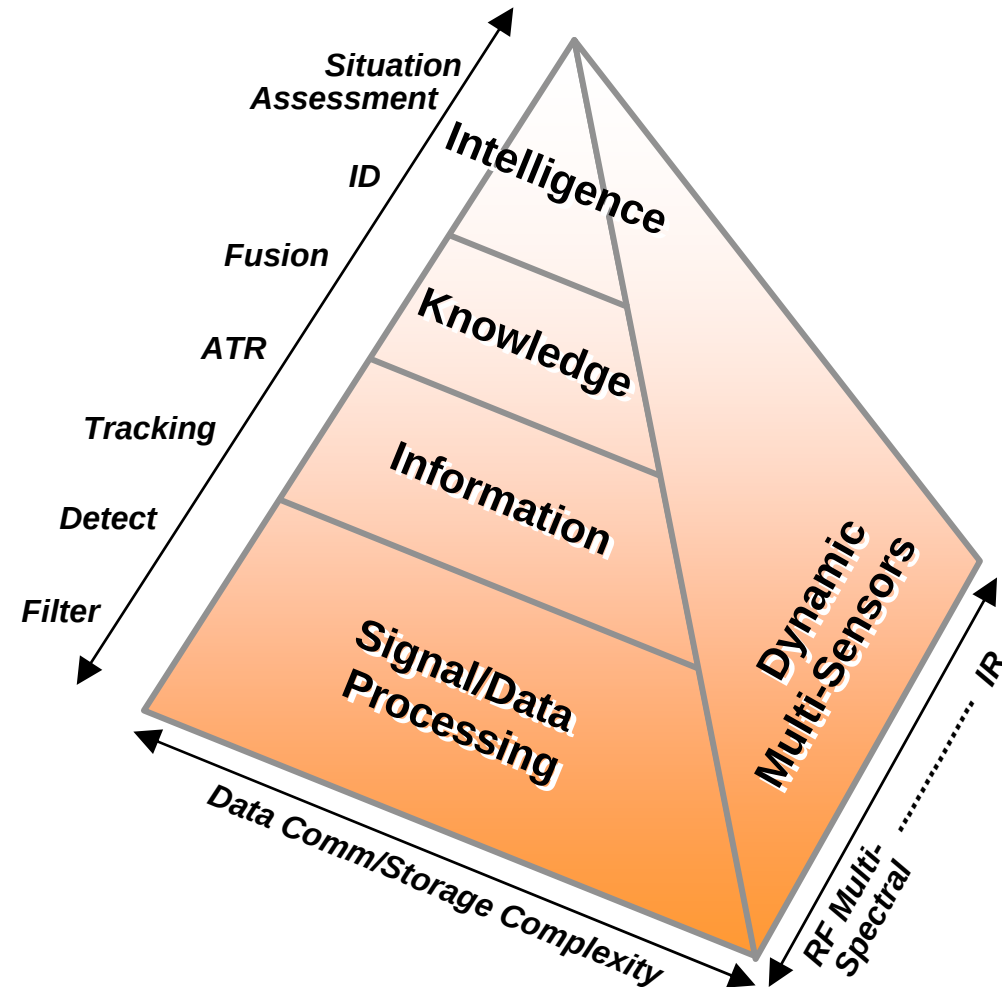
Gordon Moore Recent Comments*:

- **“You know, engineers, we’re always way too optimistic in the short run. But in the long run, it will evolve much further than we can see now.”**
- **“ I can never see more than about three generations.... The generation now is a couple of years....So I can see six to eight years further.”**

*** Excerpt from: “Two pioneers Discuss Moore’s Law and the Birth of an Industry,” 40th Anniversary of Moore’s Law, at the Computer History Museum, participants Dr. Gordon Moore and Dr. Carver Mead, Microprocessor Report Oct. 2005.**



HPEC Spanning a Broader Spectrum of Application





Changes in Force Structure*

- Navy Example -

Today

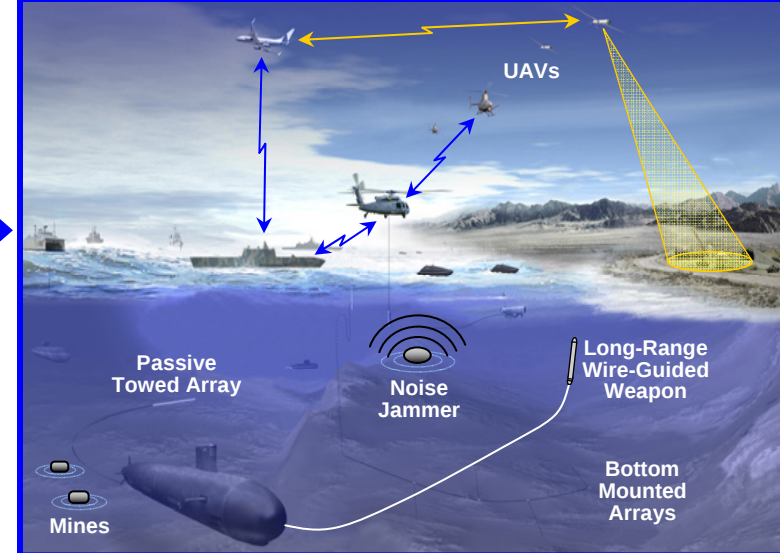
Platform-Centric



Evolving

Tomorrow

Network-Centric



- Stove-pipes

- Limited flexibility to adapt to new missions

- Large foot-print

- Network-based vs. hub and spoke model

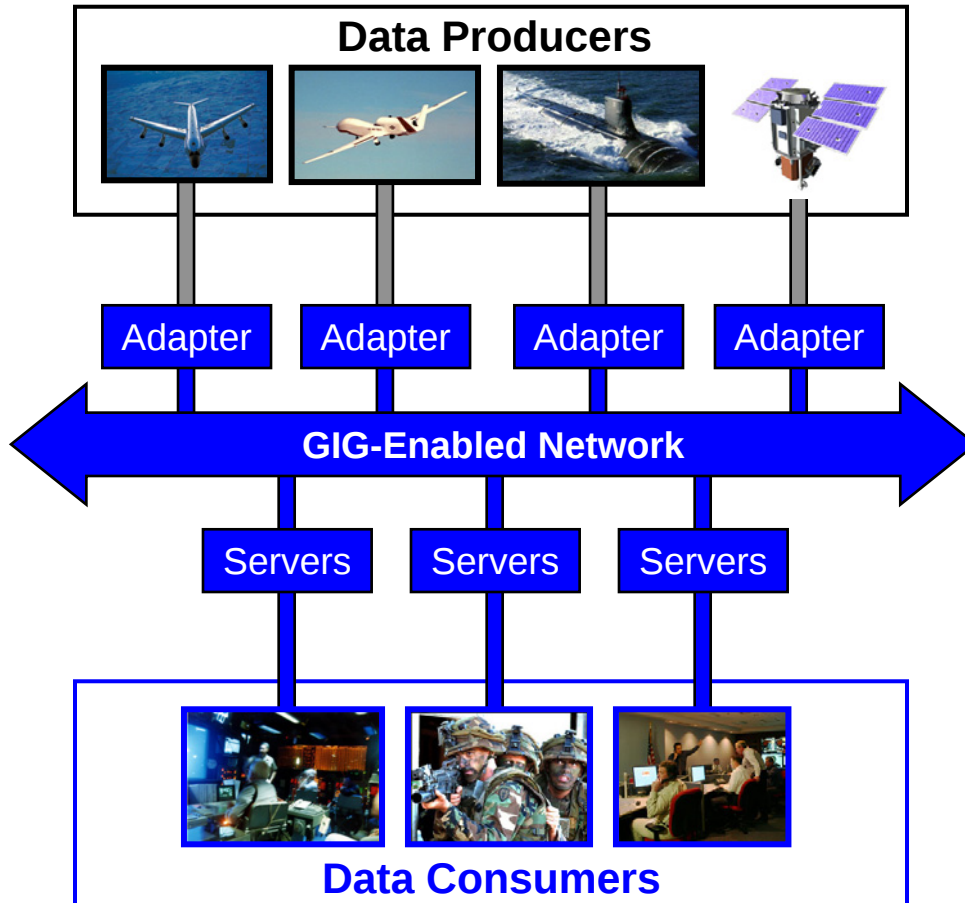
- Global connectivity and continuous information sharing

- Expeditionary forces



Migrating to a Net-Centric Architecture

Global Information Sharing



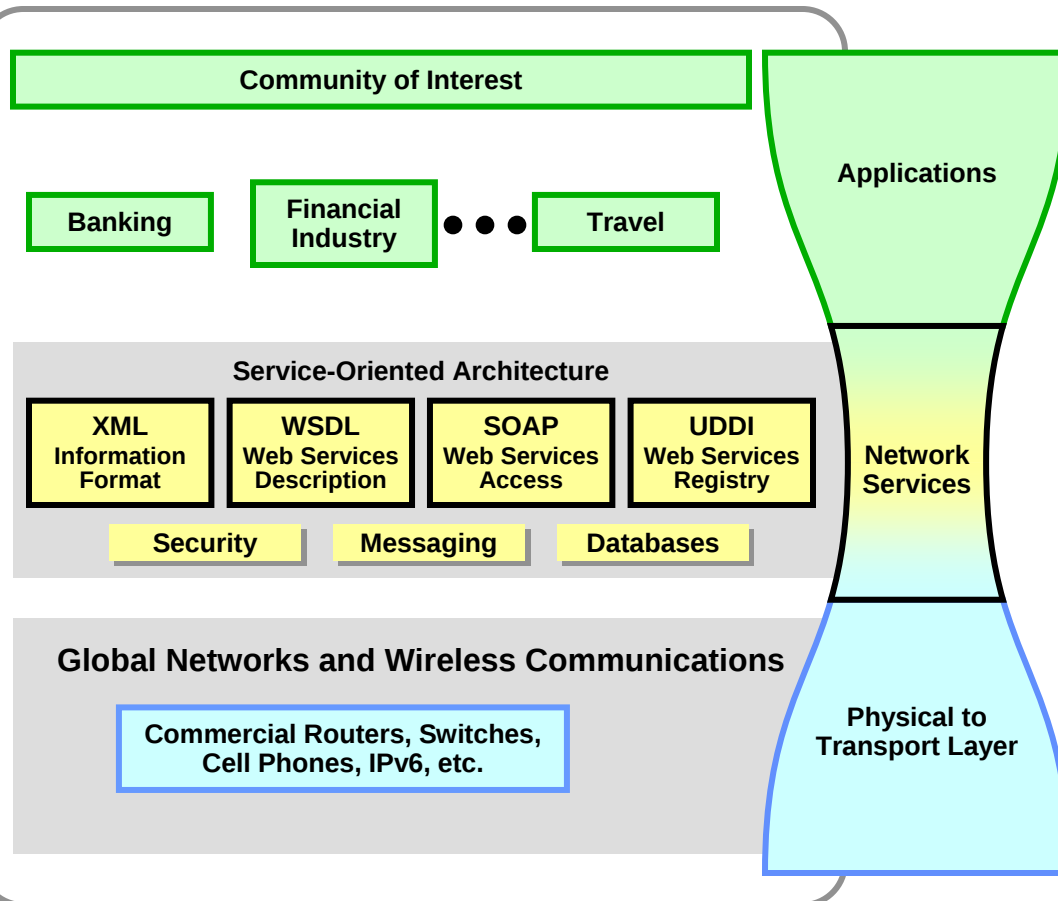
Net-Centric Technologies

- **Commercial sector**
 - Service oriented architectures
 - Web services
 - Terrestrial and wireless comms
 - Semantic Web
- **Military sector**
 - **Global Information Grid**
 - GIG-Bandwidth Expansion (terrestrial)
 - Joint Tactical Radio System
 - Transformational Satellite (TSAT)
 - Network Centric Enterprise Services (Core enterprise services to the GIG)
 - Information Assurance (encryption)
 - Teleport (theater, reach-back)
 - Joint network management system (joint network management tools)



Building from a Commercial Service-Oriented Architecture

Commercial Enterprise



* NCES = Net-Centric Enterprise Services

* HAIP = High Assurance IP Encryption Hardware

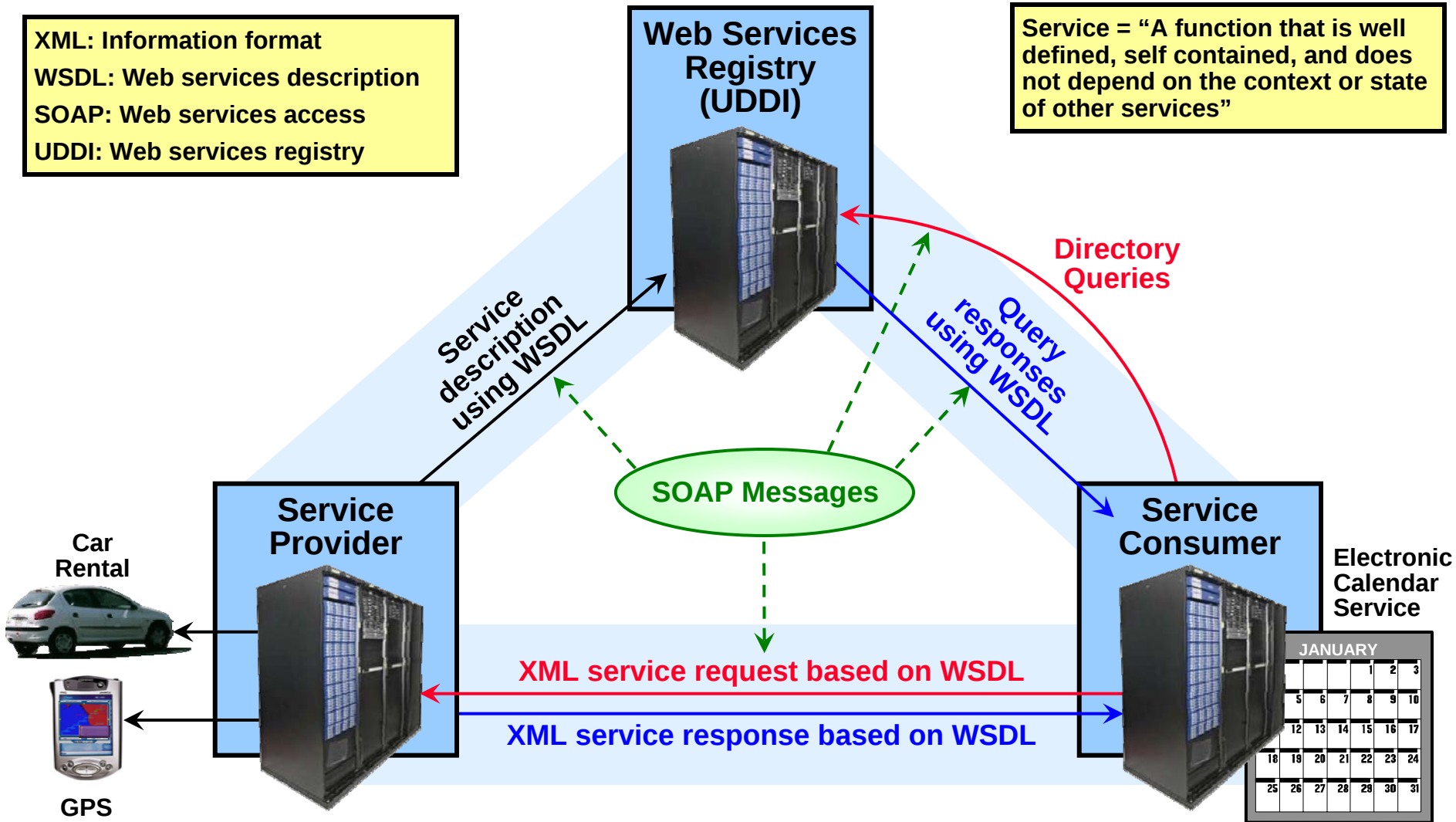
* GIG = Global Information Grid



Web Services Basics*

XML: Information format
WSDL: Web services description
SOAP: Web services access
UDDI: Web services registry

Service = "A function that is well defined, self contained, and does not depend on the context or state of other services"



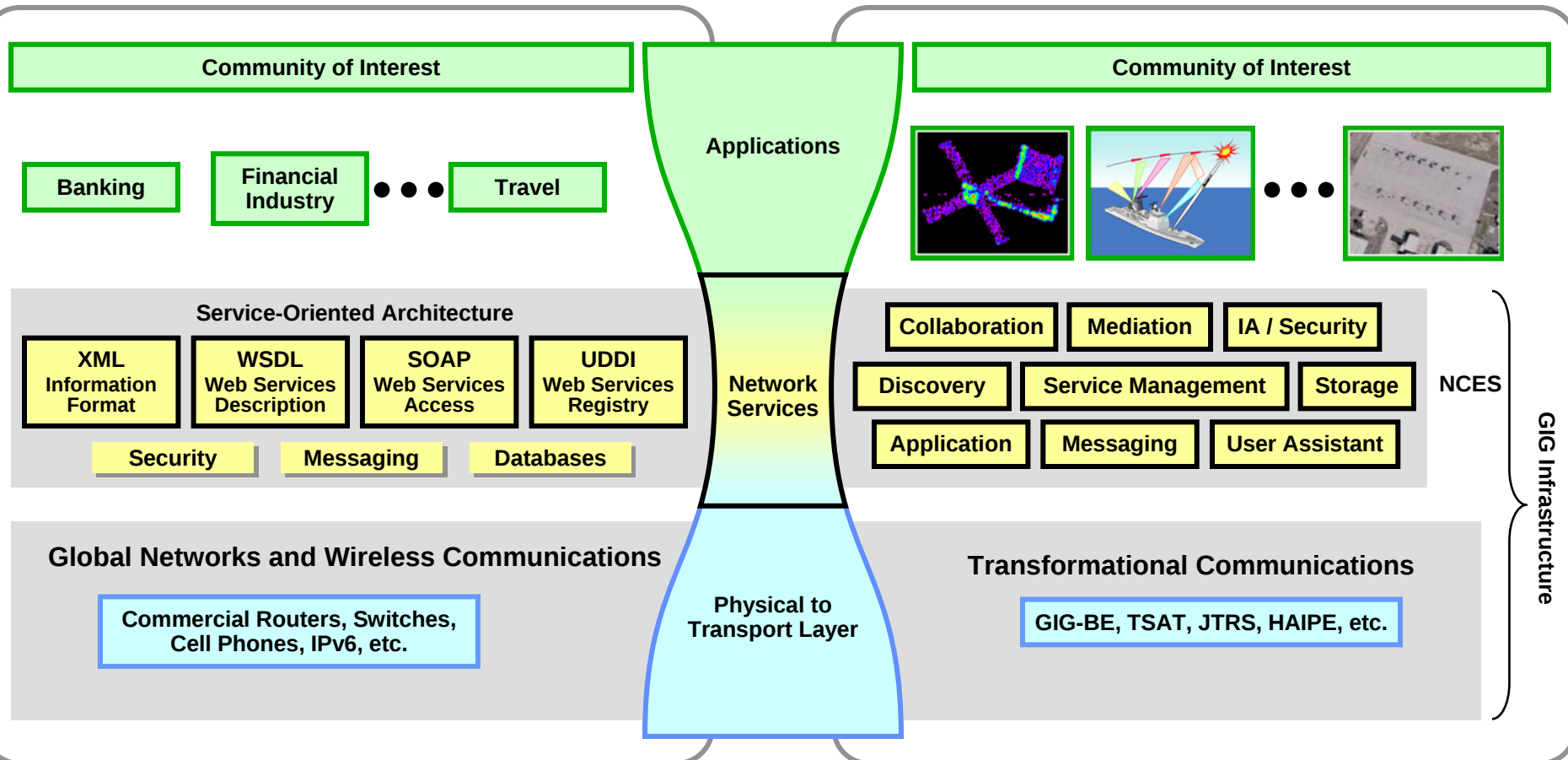
* From Web Services and Service-Oriented Architectures, D. K. Barry, 2003



Building from a Commercial Service-Oriented Architecture

Commercial Enterprise

Military Enterprise



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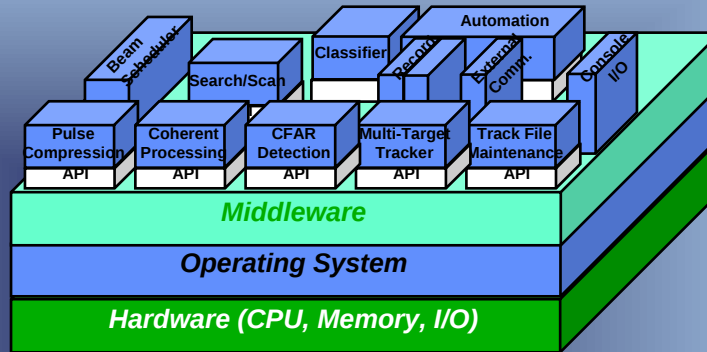
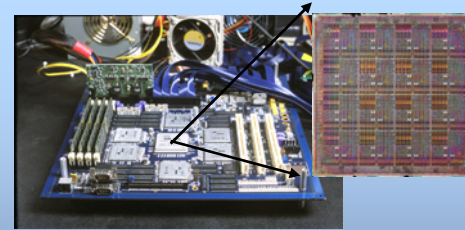
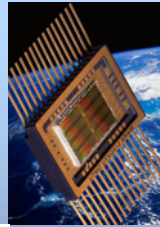
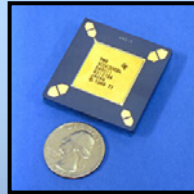
* GIG = Global Information Grid



HPEC Opportunities

Advanced HW

- FPGAs, Standard Cell ASICs for high-performance front-end sensor processing
- Mixed circuit & custom VLSI at the sensor extreme front-end



Programmable Processors

- GPUs, Cell, Clearspeed, PCAs
- Rad tolerance
- Low power
- Anti-tamper

Development Tools

- Co-design, co-development of hybrid processors
- Model-driven architectures
- Rapid-prototyping tools

Systems

- Smart sensors with knowledge-based processing
- Service-oriented sensors
- Collaborative HPEC in scalable networks
- Multi-function, multi-modal agility

Software

- Runtime environments for hybrid systems
- Intelligent middleware for on-line optimization
- Middleware for GPUs, PCAs, Cell,...



Summary

- **High performance embedded computing has gone through a significant evolution over the last 15 years**
 - Started as a principally a custom-based set of solutions
 - The evolution forced a more COTS-based solution
 - Meeting today's requirements demands a hybrid solution
- **The new set of conflicts (e.g. GWOT) is demanding much rapid deployment cycle**
 - Enemy changes tactics too fast compared to our acquisition cycle
- **The DoD landscape will continue to demand significant embedded computing capabilities**
 - A wide spectrum of solutions are available ranging from programmable processors, rapidly reconfigurable FPGAs, to custom VLSI designs
- **One emerging area is in distributed computing in support of net-centric architectures**
 - Many TeraOps in computation
 - Distributed memory and archiving
 - Fast I/O and interconnects